

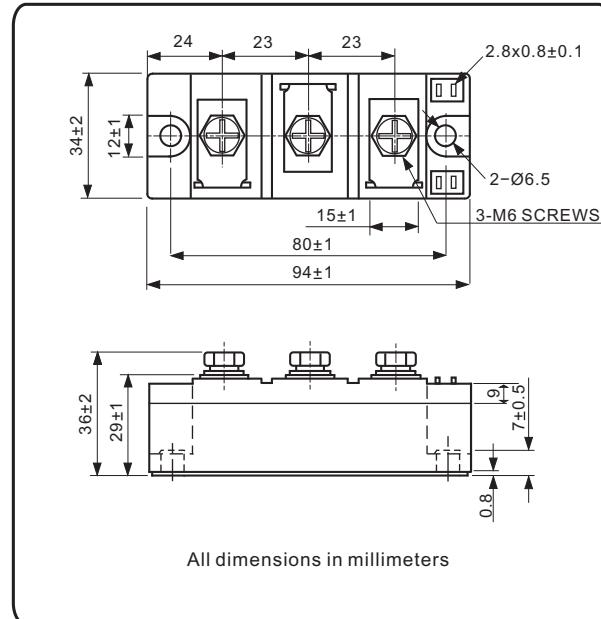
Thyristor/Diode and Thyristor/Thyristor, 160A (New INT-A-PAK Power Modules)



New INT-A-PAK

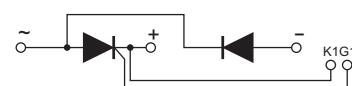
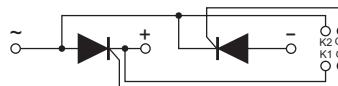
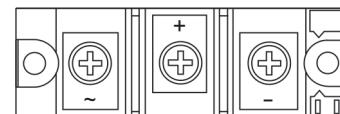
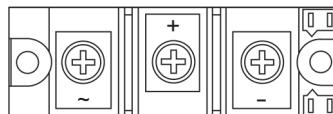
FEATURES

- High voltage
- Electrically isolated by DBC ceramic (Al_2O_3)
- 3500 V_{RMS} isolating voltage
- Industrial standard package
- High surge capability
- Glass passivated chips
- Modules uses high voltage power thyristor/diodes in two basic configurations
- Simple mounting
- UL approved file E320098 
- Compliant to RoHS
- Designed and qualified for multiple level



NKT

NKH


PRODUCT SUMMARY

I _{T(AV)}	160 A
--------------------	-------

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUE	UNITS
I _{T(AV)}	85 C	160	A
I _{T(RMS)}	85 C	251	
I _{TSM}	50 Hz	5400	A
	60 Hz	5670	
I ² t	50 Hz	146	kA ² s
	60 Hz	133	
I ² √t		1458	kA ² √s
V _{DRM} / V _{RRM}	Range	400 to 1600	V
T _J	Range	-40 to 125	C

ELECTRICAL SPECIFICATIONS

VOLTAGE RATINGS				
TYPE NUMBER	VOLTAGE CODE	V_{RRM}/V_{DRM}, MAXIMUM REPETITIVE PEAK REVERSE VOLTAGE V	V_{RSM}/V_{DSM}, MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I_{RRM}/I_{DRM} AT 125 °C mA
NKT160 NKH160	04	400	500	20
	08	800	900	
	12	1200	1300	
	14	1400	1500	
	16	1600	1700	

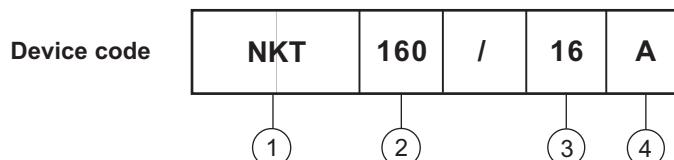
FORWARD CONDUCTION								
PARAMETER	SYMBOL	TEST CONDITIONS			VALUE	UNITS		
Maximum average on-state current at case temperature	$I_T(AV)$	180° conduction, half sine wave, 50Hz			160	A		
					85	°C		
Maximum RMS on-state current	$I_T(RMS)$	180° conduction, half sine wave, 50Hz, $T_C = 85^\circ C$			251	A		
Maximum peak, one-cycle, on-state non-repetitive surge current	I_{TSM}	$t = 10 \text{ ms}$	No voltage reapplied	Sine half wave, initial $T_J = T_J$ maximum	5400	A		
		$t = 8.3 \text{ ms}$			5670			
Maximum I^2t for fusing	I^2t	$t = 10 \text{ ms}$	100% V_{RRM} reapplied	Sine half wave, initial $T_J = T_J$ maximum	146	kA^2s		
		$t = 8.3 \text{ ms}$			133			
		$t = 10 \text{ ms}$			102			
		$t = 8.3 \text{ ms}$			93			
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	$t = 0.1 \text{ ms to } 10 \text{ ms}$, no voltage reapplied			1458	$\text{kA}^2\sqrt{\text{s}}$		
Maximum on-state voltage drop	V_{TM}	$I_{TM} = 480 \text{ A}$, $T_J = 25^\circ C$, 180° conduction			1.7	V		
Maximum forward voltage drop	V_{FM}	$I_{FM} = 480 \text{ A}$, $T_J = 25^\circ C$, 180° conduction			1.4			
Maximum holding current	I_H	Anode supply = 6 V initial $I_T = 30 \text{ A}$, $T_J = 25^\circ C$			40~150	mA		
Maximum latching current	I_L	Anode supply = 6 V resistive load = 1 Ω Gate pulse: 10 V, 100 μs, $T_J = 25^\circ C$			400			

BLOCKING					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum peak reverse and off-state leakage current	I_{RRM}, I_{DRM}	$T_J = 125^\circ C$		20	mA
RMS isolation Voltage	V_{ISO}	50 Hz, circuit to base, all terminals shorted		2500 (1min) 3500 (1s)	V
Critical rate of rise of off-state voltage	dV/dt	$T_J = T_J$ maximum, exponential to 67% rated V_{DRM}		800	$\text{V}/\mu\text{s}$

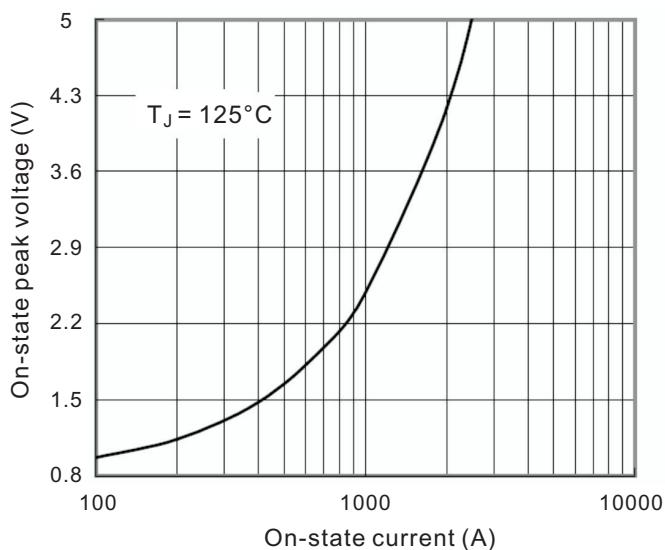
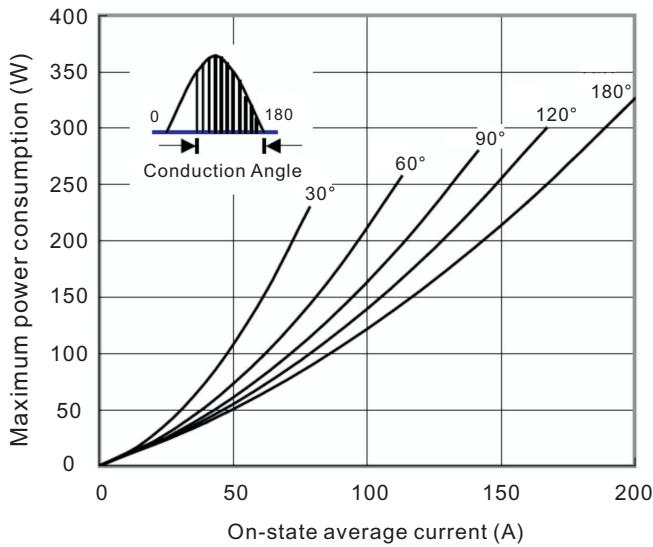
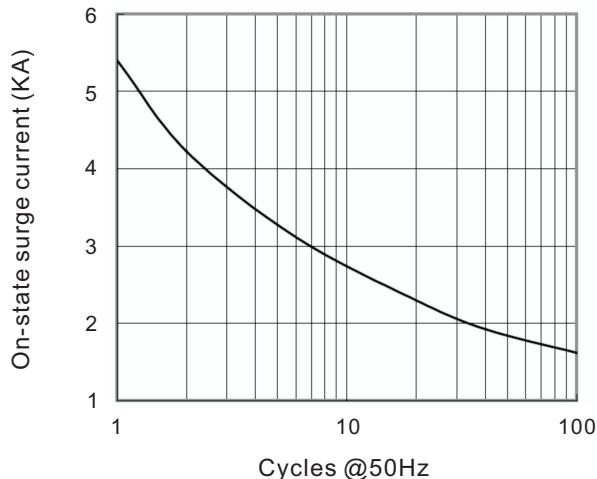
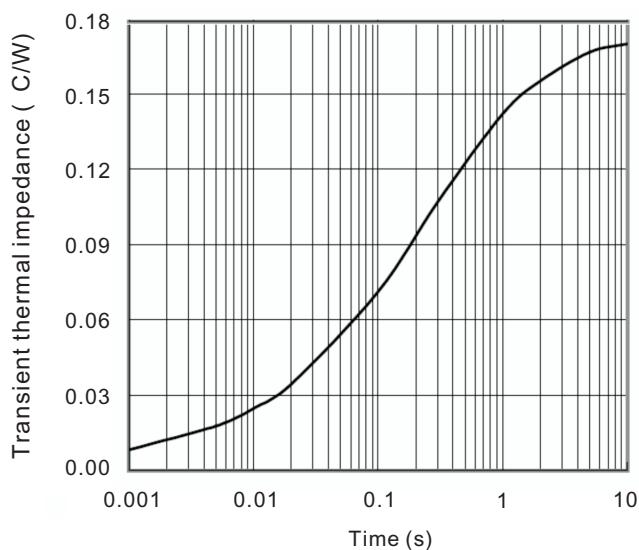
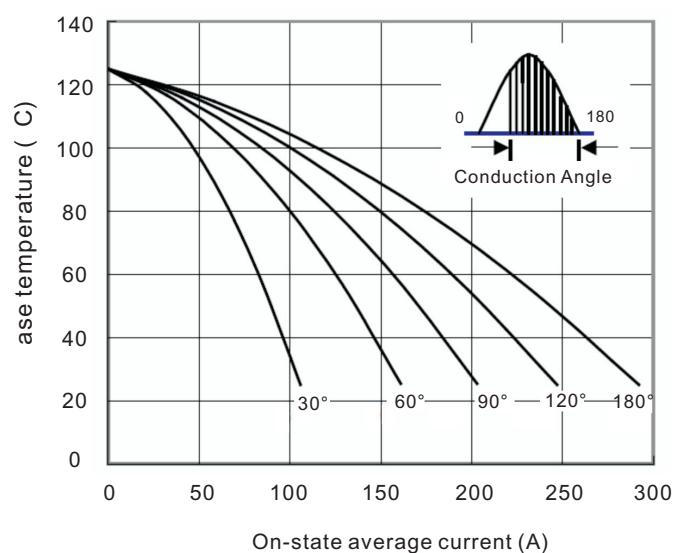
Nell High Power Products

TRIGGERING					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum peak gate power	P _{GM}	$t_p \leq 5 \text{ ms}$, $T_J = T_{J\text{ maximum}}$		10	W
Maximum average gate power	P _{G(AV)}	$f = 50 \text{ Hz}$, $T_J = T_{J\text{ maximum}}$		3	
Maximum peak gate current	I _{GM}	$t_p \leq 5 \text{ ms}$, $T_J = T_{J\text{ maximum}}$		3	A
Maximum peak negative gate voltage	-V _{GT}			10	V
Maximum required DC gate voltage to trigger	V _{GT}	T _J = 25°C	Anode supply = 6 V, resistive load; R _a = 1Ω	0.7~1.8	
Maximum required DC gate current to trigger	I _{GT}			30~150	mA
Maximum gate voltage that will not trigger	V _{GD}	T _J = T _J maximum, 66.7% V _{DRM} applied		0.25	V
Maximum gate current that will not trigger	I _{GD}			10	mA
Maximum rate of rise of turned-on current	dI/dt	T _J = 25°C, I _{GM} = 1.5A, t _r ≤ 0.5 μs		150	A/μs

THERMAL AND MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction operating temperature range	T _J		- 40 to 125	C
Maximum storage temperature range	T _{Stg}		- 40 to 150	
Maximum thermal resistance, junction to case per junction	R _{thJC}	DC operation	0.17	C/W
Maximum thermal resistance, case to heatsink per module	R _{thCS}		0.055	
Mounting torque 10 % IAP to heatsink , M6 busbar to IAP , M6		A mounting compound is recommended and the torque should be rechecked after a period of 3 hours to allow for the spread of the compound. Lubricated threads.	4 to 6	N.m
Approximate weight			220	g
			7.05	oz.
Case style				New INT-A-PAK

ORDERING INFORMATION TABLE


- [1] - Module type: NKT for (Thyristor + Thyristor) module
NKH for (Thyristor + Diode) module
- [2] - Current rating: I_{T(AV)}
- [3] - Voltage code x 100 = V_{RRM}
- [4] - Assembly type,"A" for soldering type

Nell High Power Products
Fig.1 On-state current vs. voltage characteristic

Fig.3 Power consumption vs. average current

Fig.5 On-state surge current vs cycles

Fig.2 Transient thermal impedance(junction-case)

Fig.4 Case temperature vs. on-state average current

Fig.6 Gate characteristics
